

1. Product Features

1.1 Electrical features

- $V_{CES}=1200V$
- $I_{C\ nom}=75A / I_{CRM}=150A$
- Low switching losses
- Low inductance
- Fast switching and short tail current
- High power and thermal cycling capability



Figure1 IGBT Module

1.2 Mechanical features

- Al_2O_3 substrate with low thermal resistance
- Copper base plate

2. Typical Applications

- High Frequency Switching Application
- Motor drives
- UPS system

3. Description

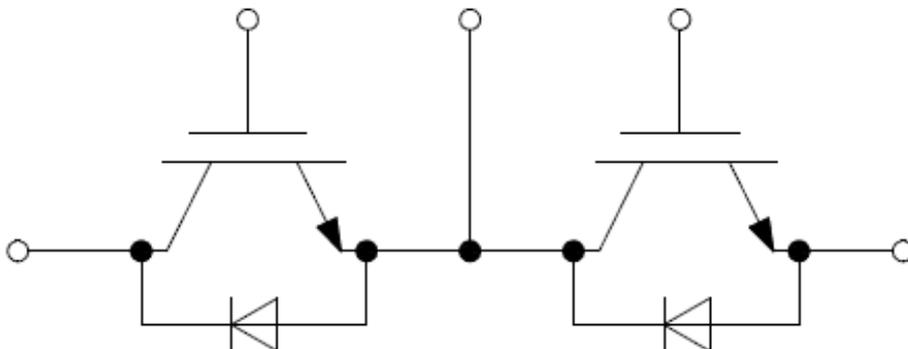


Figure 2 Half Bridge

4. IGBT, Inverter

4.1 Maximum Rated Values

Parameter	Note or test condition	Symbol	Values	Unit
Collector-emitter voltage 集电极—发射极间电压	$T_{vj} = 25^{\circ}\text{C}$	V_{CES}	1200	V
Continuous DC collector current 连续集电极电流	$T_C = 100^{\circ}\text{C}, T_{vj} \text{ max} = 150^{\circ}\text{C}$	$I_{C \text{ nom}}$	75	A
Repetitive peak collector current 集电极峰值电流	$t_P = 1 \text{ ms}$	I_{CRM}	150	A
Total power dissipation 总功率损耗	$T_C = 25^{\circ}\text{C}, T_{vj} \text{ max} = 175^{\circ}\text{C}$	P_{tot}	395	W
Gate-emitter peak voltage 栅极—发射极峰值电压		V_{GES}	+/- 20	V

4.2 Characteristic value

Parameter	Note or test condition	Symbol	Values			Unit	
			Min.	Typ.	Max.		
Collector-emitter saturation voltage 集电极—发射极饱和电压	$I_C = 75 \text{ A}, V_{GE} = 15 \text{ V}$	$V_{CE, \text{sat}}$		$T_{vj} = 25^{\circ}\text{C}$	1.63		V
				$T_{vj} = 125^{\circ}\text{C}$	1.65		V
				$T_{vj} = 150^{\circ}\text{C}$	1.70		V
Gate threshold voltage 栅极阈值电压	$I_C = 2.8 \text{ mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$	$V_{GE, \text{th}}$	5.0	6.0	6.5	V	
Gate charge 栅极电荷	$V_{GE} = -15 \text{ V} \dots +15 \text{ V}$	Q_G		0.81		μC	
Internal gate resistor 内部栅极电阻	$T_{vj} = 25^{\circ}\text{C}$	$R_{G \text{ int}}$		2.70		Ω	
Input capacitance 输入电容	$f = 1 \text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}$	C_{ies}		9.80		nF	
Reverse transfer capacitance 反向传输电容	$f = 1 \text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}$	C_{res}		0.12		nF	
Collector-emitter cut-off current 集电极-发射极截止电流	$V_{CE} = 1200 \text{ V}, V_{GE} = 0 \text{ V}, T_{vj} = 25^{\circ}\text{C}$	I_{CES}			1	mA	
Gate-emitter leakage current 栅极-发射极漏电流	$V_{CE} = 0 \text{ V}, V_{GE} = 20 \text{ V}, T_{vj} = 25^{\circ}\text{C}$	I_{GES}			100	nA	
Turn-on delay time, inductive load 开通延迟时间	$I_C = 75 \text{ A}, V_{CE} = 600 \text{ V}$ $V_{GE} = +15/-15 \text{ V}$ $R_{G, \text{on}} = 9.1 \Omega$	$t_{d, \text{on}}$		$T_{vj} = 25^{\circ}\text{C}$	0.13		us
				$T_{vj} = 125^{\circ}\text{C}$	0.13		us
				$T_{vj} = 150^{\circ}\text{C}$	0.14		us
Rise time, inductive load 上升时间	$I_C = 75 \text{ A}, V_{CE} = 600 \text{ V}$ $V_{GE} = +15/-15 \text{ V}$ $R_{G, \text{on}} = 9.1 \Omega$	t_r		$T_{vj} = 25^{\circ}\text{C}$	0.05		us
				$T_{vj} = 125^{\circ}\text{C}$	0.05		us
				$T_{vj} = 150^{\circ}\text{C}$	0.05		us

(table continues...) 待续

Parameter	Note or test condition	Symbol	Values			Unit
			Min.	Typ.	Max.	
Turn-off delay time, inductive load 关断延迟时间	$I_C = 75A, V_{CE} = 600V$ $V_{GE} = +15/-15V$ $R_{G,on} = 9.1\Omega$	$T_{vj} = 25^\circ C$ $T_{vj} = 125^\circ C$ $T_{vj} = 150^\circ C$	$t_{d,off}$		0.33	us
					0.34	us
					0.34	us
Fall time, inductive load 下降时间	$I_C = 75A, V_{CE} = 600V$ $V_{GE} = +15/-15V$ $R_{G,on} = 9.1\Omega$	$T_{vj} = 25^\circ C$ $T_{vj} = 125^\circ C$ $T_{vj} = 150^\circ C$	t_f		0.22	us
					0.29	us
					0.29	us
Turn-on energy loss per pulse 开通损耗能量	$I_C = 75A, V_{CE} = 600V, L_s = 30nH$ $V_{GE} = +15/-15V, di/dt = 1200A/\mu s$ $R_{G,on} = 9.1\Omega (T_{vj} = 150^\circ C)$	$T_{vj} = 25^\circ C$ $T_{vj} = 125^\circ C$ $T_{vj} = 150^\circ C$	E_{on}		7.25	mJ
					8.61	mJ
					9.48	mJ
Turn-off energy loss per pulse 关断损耗能量	$I_C = 75A, V_{CE} = 600V, L_s = 30nH$ $V_{GE} = +15/-15V, dv/dt = 4485V/\mu s$ $R_{G,off} = 9.1\Omega (T_{vj} = 150^\circ C)$	$T_{vj} = 25^\circ C$ $T_{vj} = 125^\circ C$ $T_{vj} = 150^\circ C$	E_{off}		6.10	mJ
					8.08	mJ
					8.38	mJ
SC data 短路数据	$V_{GE} \leq 15V, V_{CC} = 600V, t_p \leq 8\mu s, T_{vj} = 150^\circ C,$ $C_{GE} = 0.0\mu F, V_{CEmax} = V_{CES} - L_{SCE} \cdot di/dt$	I_{SC}		668		A
Thermal resistance, junction to case 结—外壳热阻	Per IGBT	$R_{th,jc}$			0.38	K/W

5. Diode, Inverter

5.1 Maximum Rated Values

Parameter	Note or test condition	Symbol	Values	Unit
Repetitive peak reverse voltage 反向重复峰值电压	$T_{vj} = 25^\circ C$	V_{RRM}	1200	V
Continuous DC forward current 连续正向直流电流		I_F	75	A
Repetitive peak forward current 正向重复峰值电流	$t_p = 1\text{ ms}$	I_{FRM}	150	A

5.2 Characteristic value

Parameter	Note or test condition	Symbol	Values			Unit
			Min.	Typ.	Max.	
Forward voltage 正向电压	$I_F = 75A, V_{GE} = 0V$	V_F		1.66	V	
				1.67	V	
				1.62	V	

(table continues...) 待续

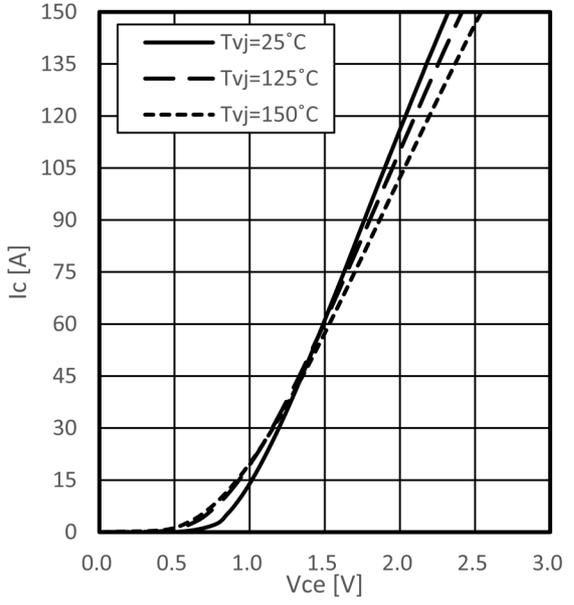
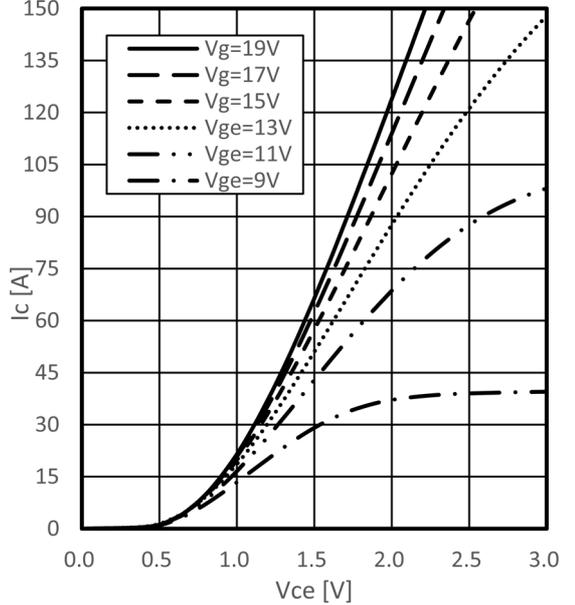
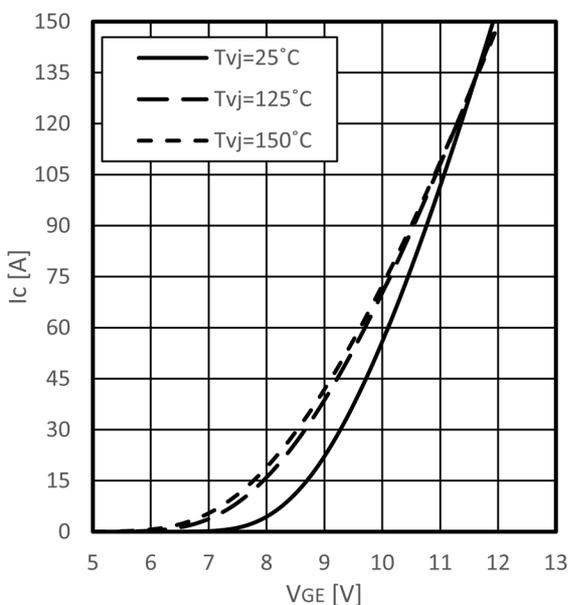
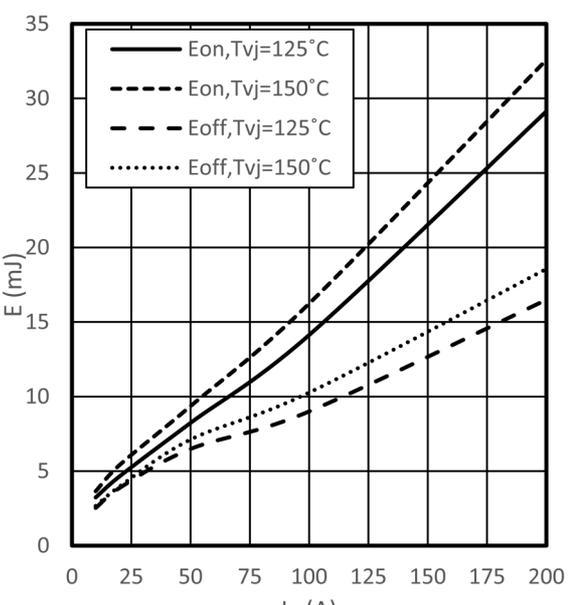
Parameter	Note or test condition	Symbol	Values			Unit
			Min.	Typ.	Max.	
Peak reverse recovery current 反向恢复峰值电流	$I_F = 75A, V_R = 600V$	$T_{vj} = 25^\circ C$		70.5		A
	$V_{GE} = -15V, -di_F/dt = 1430 A/\mu s$	$T_{vj} = 125^\circ C$		89.2		A
	$R_{G,off} = 9.1\Omega (T_{vj} = 150^\circ C)$	$T_{vj} = 150^\circ C$		92.4		A
Recovered charge 恢复电荷	$I_F = 75A, V_R = 600V$	$T_{vj} = 25^\circ C$		4.69		μC
	$V_{GE} = -15V, -di_F/dt = 1430 A/\mu s$	$T_{vj} = 125^\circ C$		8.63		μC
	$R_{G,off} = 9.1\Omega (T_{vj} = 150^\circ C)$	$T_{vj} = 150^\circ C$		10.9		μC
Reverse recovery energy 反向恢复损耗 (每脉冲)	$I_F = 75A, V_R = 600V$	$T_{vj} = 25^\circ C$		0.77		mJ
	$V_{GE} = -15V, -di_F/dt = 1430 A/\mu s$	$T_{vj} = 125^\circ C$		1.82		mJ
	$R_{G,off} = 9.1\Omega (T_{vj} = 150^\circ C)$	$T_{vj} = 150^\circ C$		2.62		mJ
Thermal resistance, junction to case 结-外壳热阻	Per diode	$R_{th,Jc}$			0.45	K/W

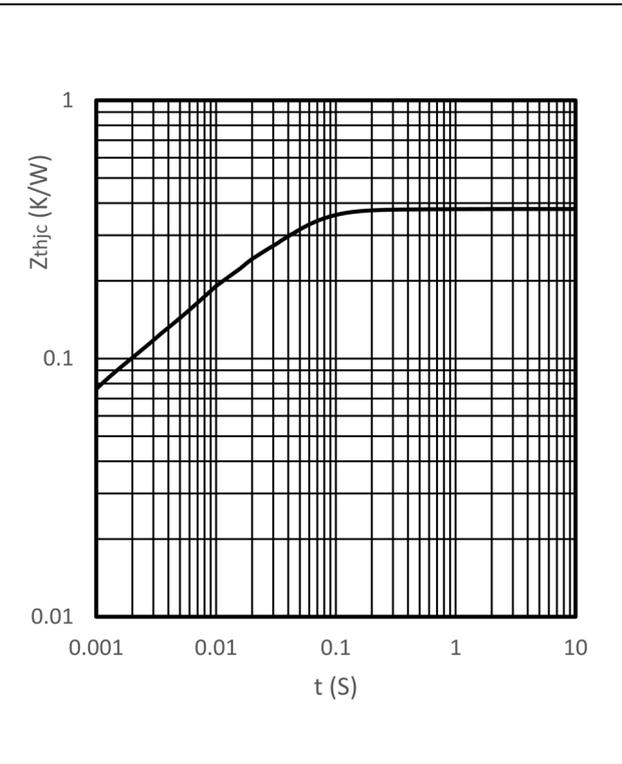
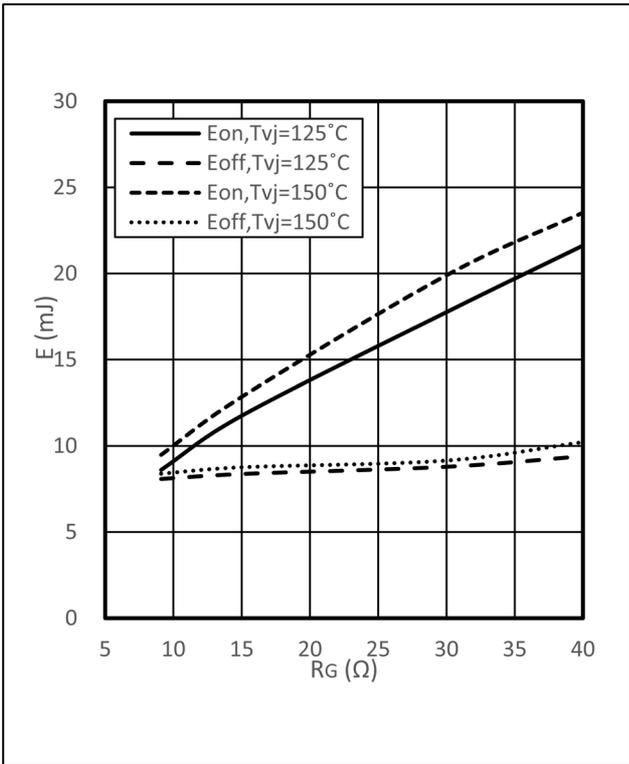
6. Module

6.1 Characteristic value

Parameter	Note or test condition	Symbol	Values			Unit
			Min.	Typ.	Max.	
Isolation Voltage 隔离电压	RMS, f=50HZ,1min	V_{ISOL}			2500	V
Stray inductance module 杂散电感		L_{sCE}		30		nH
Operation Junction Temperature 结温		T_{jop}	-40		150	$^\circ C$
Storage Temperature Range 存储温度范围		T_{stg}	-40		125	$^\circ C$
Mounting Torque 安装扭矩	Screw M6	M	3.0		5.0	N.m
Terminal Connection Torque 端子扭矩	Screw M5	M	2.5		5.0	N.m
Weight of Module 重量		G		160		g

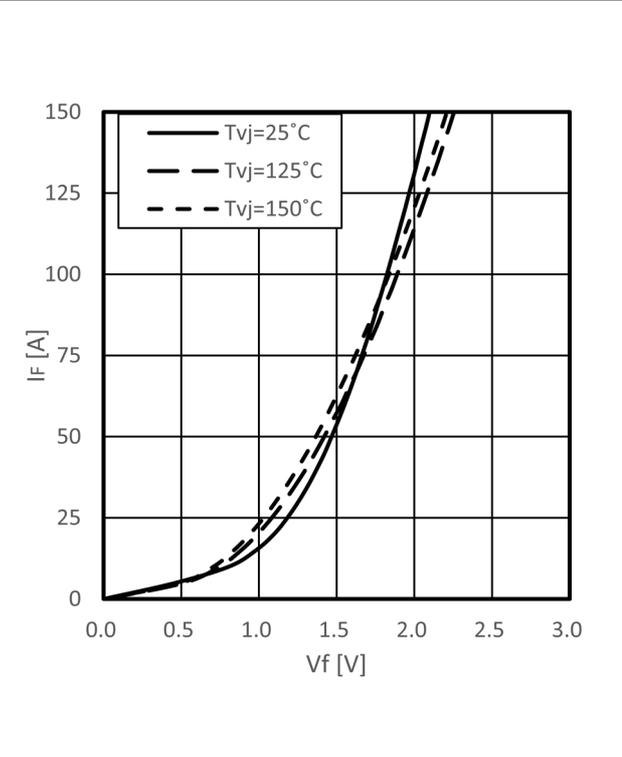
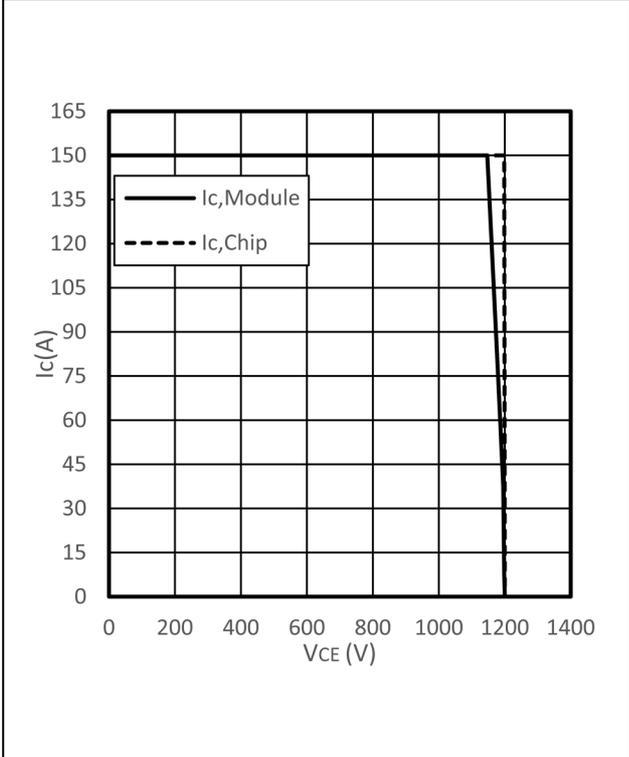
7. Characteristics Diagrams

	
<p>Output characteristic IGBT (typical) $I_c = f(V_{CE}) V_{GE} = 15V$</p>	<p>Output characteristic IGBT (typical) $I_c = f(V_{CE}) T_{vj} = 150^\circ C$</p>
	
<p>Transfer characteristic IGBT (typical) $I_c = f(V_{GE}) V_{CE} = 20V$</p>	<p>Switching losses IGBT (typical) $E_{on} = f(I_c), E_{off} = f(I_c) V_{GE} = \pm 15V, R_{Gon} = 9.1 \Omega, R_{Goff} = 9.1 \Omega, V_{CE} = 600V$</p>



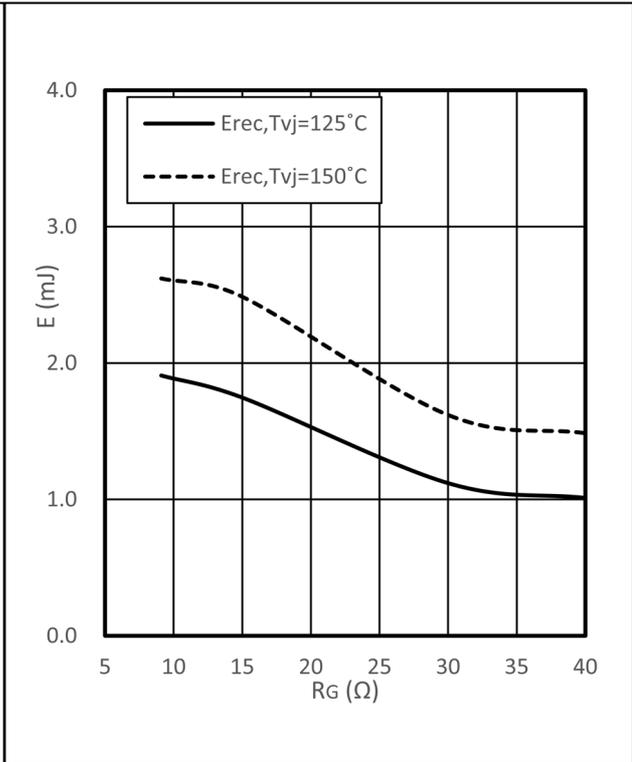
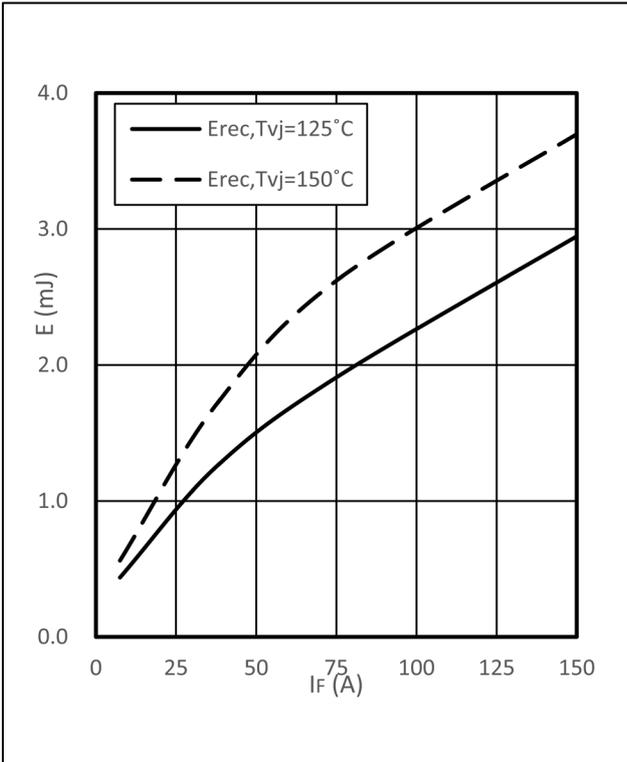
Switching losses IGBT (typical)
 $E_{on} = f(R_G)$, $E_{off} = f(R_G)V_{GE} = \pm 15V$, $I_c = 75A$, $V_{CE} = 600V$

Transient thermal impedance IGBT
 $Z_{thjc} = f(t)$



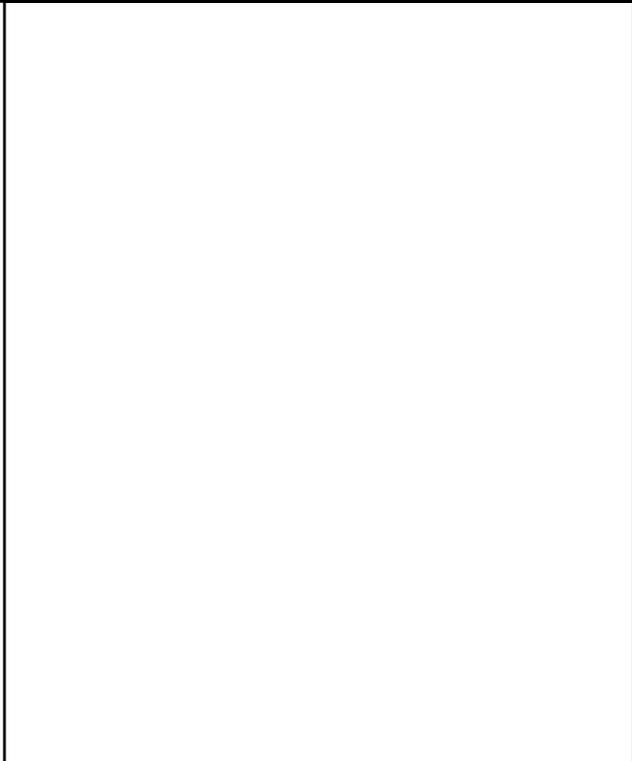
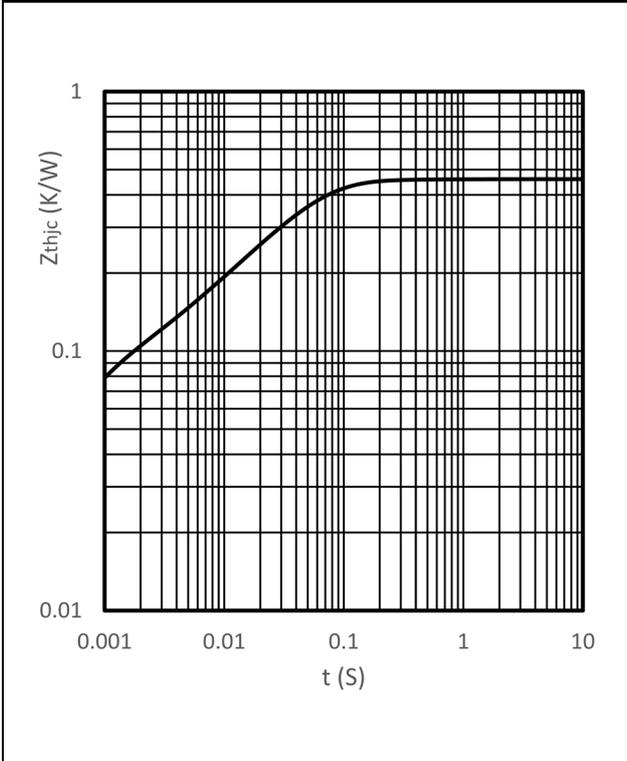
Reverse bias safe operating area IGBT (RBSOA)
 $I_c = f(V_{CE})$, $V_{GE} = \pm 15V$, $R_{Goff} = 9.1\Omega$, $T_{vj} = 150^\circ\text{C}$

Forward characteristic of Diode (typical)
 $I_F = f(V_F)$



Switching losses Diode (typical)
 $E_{rec} = f(I_F)$, $R_g = 9.1\Omega$, $V_{CE} = 600V$

Switching losses Diode (typical)
 $E_{rec} = f(R_G)$, $I_F = 75\text{ A}$, $V_{CE} = 600V$



Transient thermal impedance Diode
 $Z_{thjc} = f(t)$

8. Circuit Diagram

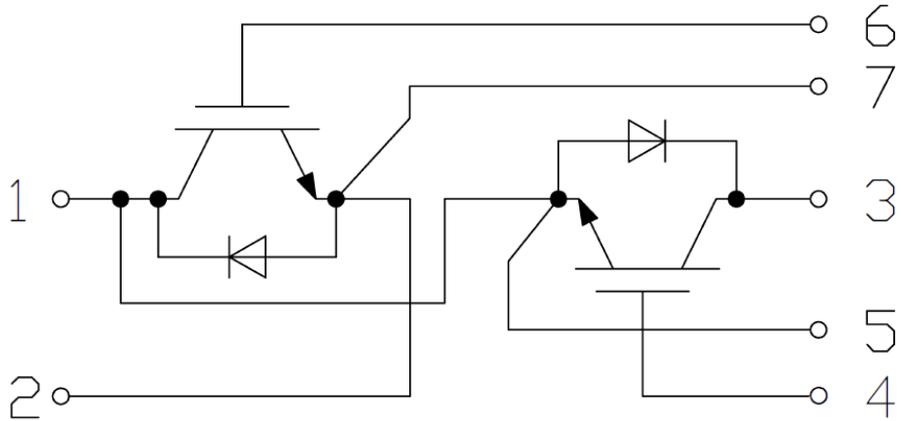


Figure 3

9. Package Outlines

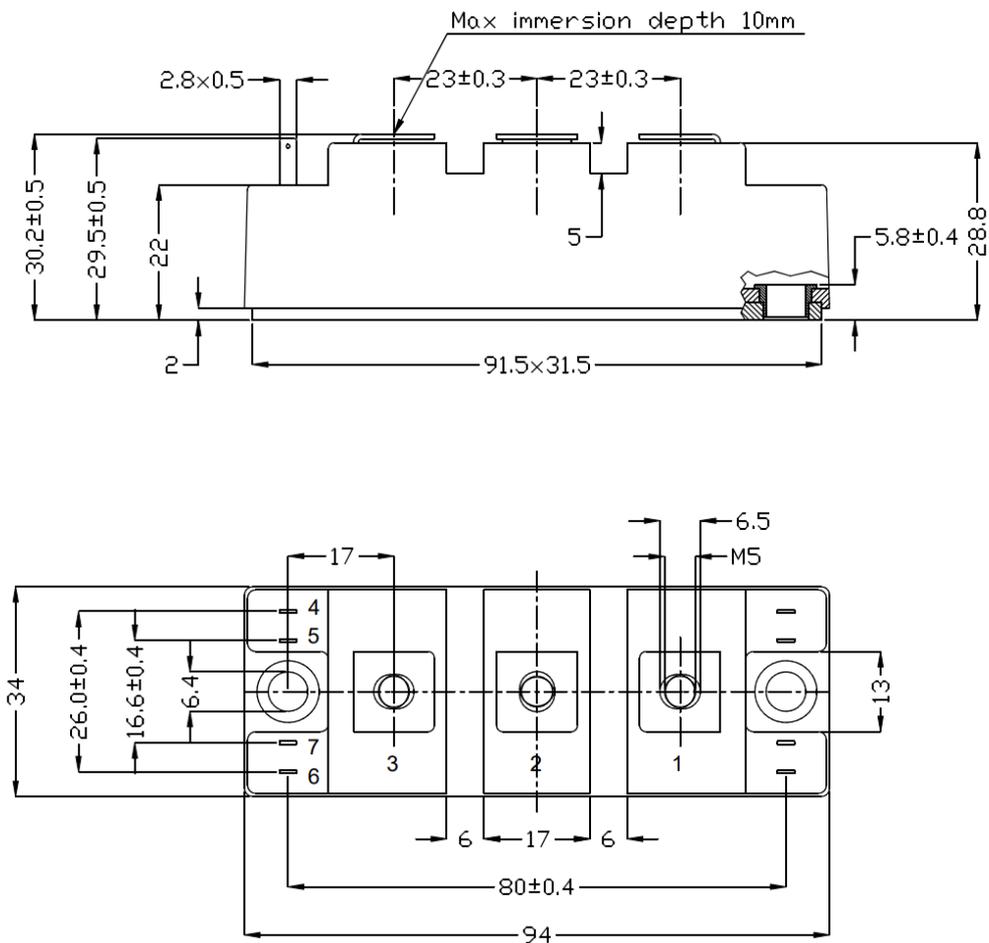


Figure 4